F-218 (Rev 13FEB18)

samtec

BSH–060–01–F–D–RA–WT

BSH–030–01–L–D–RA–WT

BSH–090–01–L–D–A

BSH–060–01–F–D–A

(0.50 mm) .0197"

BSH SERIES

BASIC BLADE & BEAM SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BSH

Insulator Material:
Black LCP
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
2 A per pin
(2 pins powered)
Flammability Rating:
UL 94 VO
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
175 VAC
Max Cycles:
100
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (030-090)
(0.15 mm) .006" max (120-150)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)
Board Stacking:
For applications requiring more
than two connectors per board
or 90 positions or higher,
contact ipg@samtec.com

RECOGNITIONS

For complete scope
of recognitions see
www.samtec.com/quality

FILE NO. E111594

ALSO AVAILABLE
(MOQ Required)

• 30 µ" (0.76 µm) Gold
• Edge Mount Capability
• 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/ inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)
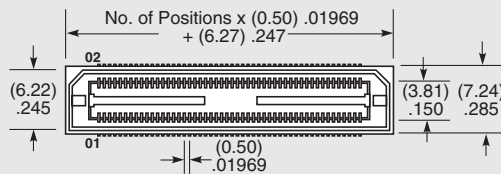Contact Samtec.

Note:
Some lengths, styles and options are non-standard, non-returnable.

| BSH | NO. OF POSITIONS PER ROW | 01 | PLATING OPTION | D | A | OTHER OPTION |

Mates with: BTH

–020, –040, –060, –090, –100, –120

No. of Positions x (0.50) .01969 + (6.27) .247

(6.22) .245
02
01
(3.81) .150
(7.24) .285
(0.50) .01969

(3.05) .120
(0.15) .006
(3.25) .128
(0.89) .035 DIA
(0.76) .030

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
–01	(5.00) .197

*Processing conditions will affect mated height.

–F
= Gold Flash on contact, Matte Tin on tail

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

–C*
= Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails

*Note: –C Plating passes 10 year MFG testing

–TR
= Tape & Reel (120 positions maximum)

POWER/SIGNAL APPLICATION

Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

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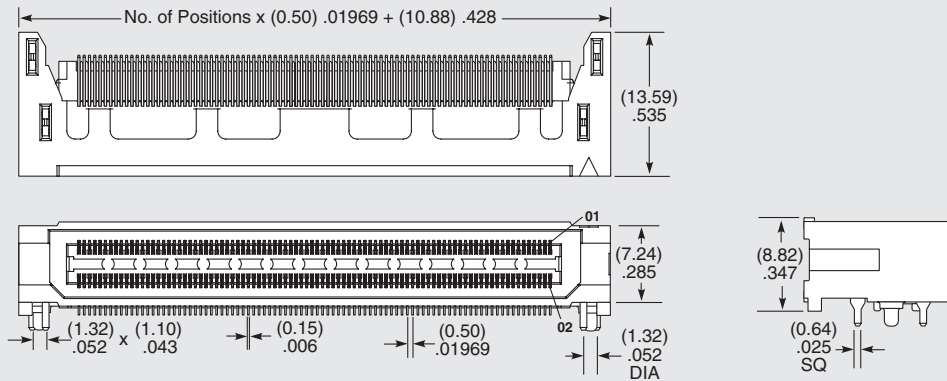| BSH | NO. OF POSITIONS PER ROW | 01 | PLATING OPTION | D | RA | WT | OTHER OPTION |

Mates with: BTH

–030, –060, –090

–F
= Gold Flash on contact, Matte Tin on tail

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

–GP
= Guide Post

No. of Positions x (0.50) .01969 + (10.88) .428

(13.59) .535

01
(7.24) .285
(8.82) .347

(1.32) .052 x (1.10) .043
(0.15) .006
(0.50) .01969
02
(1.32) .052 DIA
(0.64) .025 SQ

Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.